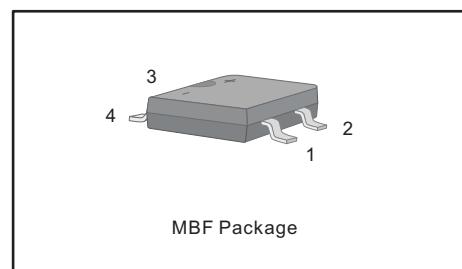


FEATURES:

- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000 V
- Forward Current - 0.8 A
- High Surge Current Capability
- Designed for Surface Mount Application

PINNING

| PIN | DESCRIPTION |
|-----|----------------------|
| 1 | Input Pin (~) |
| 2 | Input Pin (~) |
| 3 | Output Anode (+) |
| 4 | Output Cathode (-) |


MECHANICAL DATA

- Case: MBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 75mg 0.0026oz

Maximum Ratings and Electrical characteristics

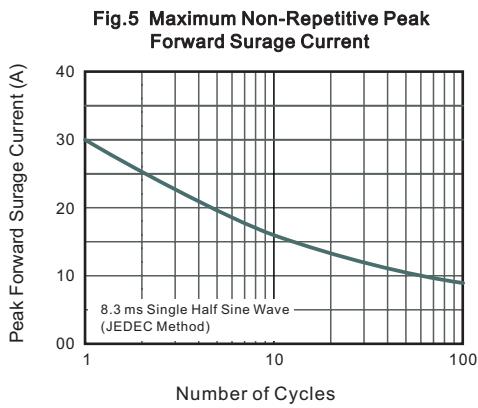
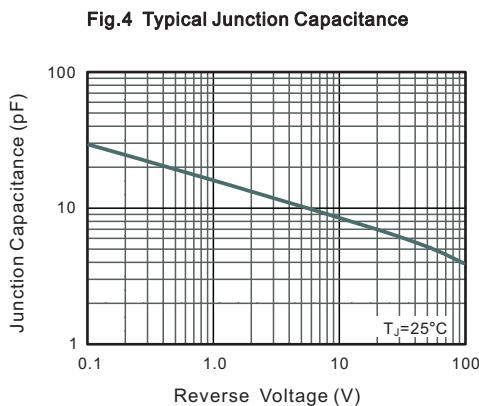
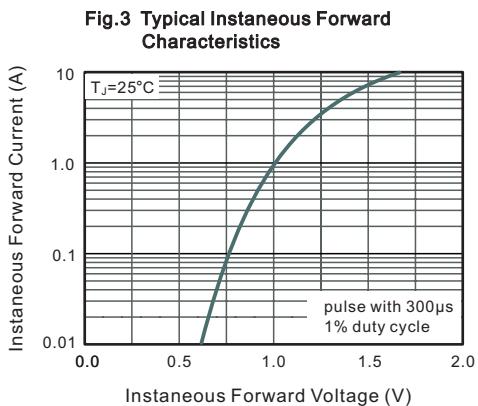
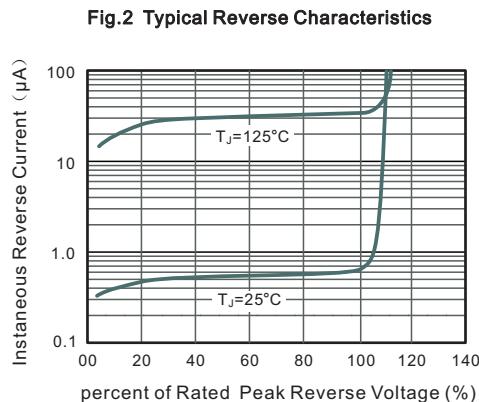
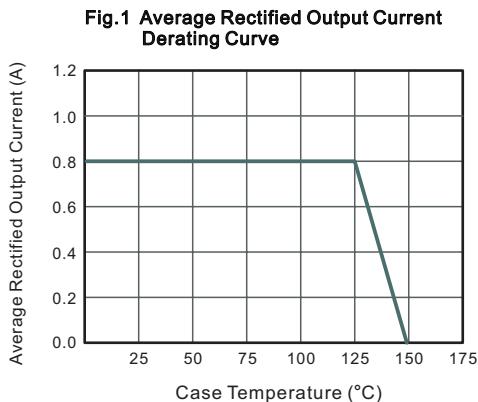
Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

| Parameter | Symbols | MB1F | MB2F | MB4F | MB6F | MB8F | MB10F | Units |
|---|------------------------------------|------------|------|------|------|------|-------|---------------|
| Maximum Repetitive Peak Reverse Voltage | V_{RRM} | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS voltage | V_{RMS} | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC Blocking Voltage | V_{DC} | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Average Rectified Output Current at $T_c = 125^\circ\text{C}$ | I_o | 0.8 | | | | | | A |
| Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method) | I_{FSM} | 30 | | | | | | A |
| Maximum Forward Voltage at 0.8 A | V_F | 1.1 | | | | | | V |
| Maximum DC Reverse Current @ $T_A = 25^\circ\text{C}$ @ $T_A = 125^\circ\text{C}$ | I_R | 5 40 | | | | | | μA |
| Typical Junction Capacitance (Note1) | C_j | 13 | | | | | | pF |
| Typical Thermal Resistance (Note2) | $R_{\theta JA}$ $R_{\theta JC}$ | 90 30 | | | | | | °C/W |
| Operating and Storage Temperature Range | T_j, T_{stg} | -55 ~ +150 | | | | | | °C |

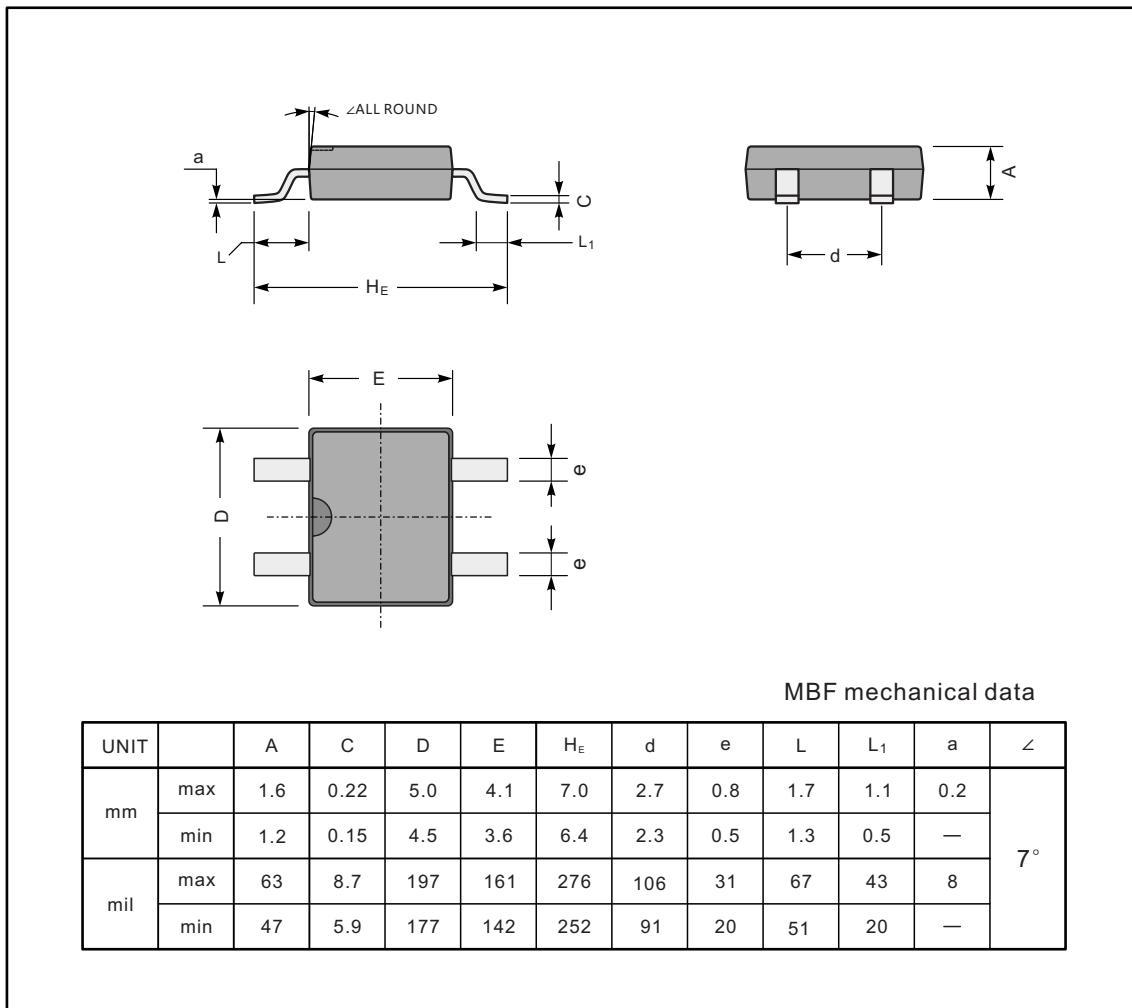
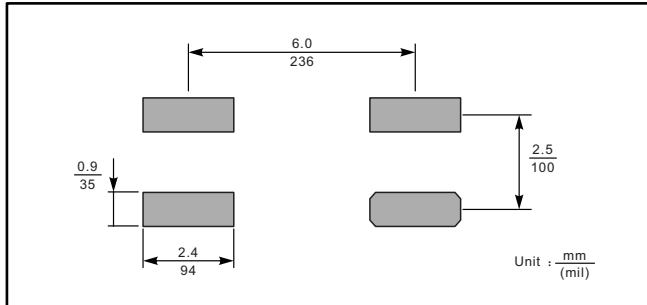
Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.



PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

MBF

The recommended mounting pad size

Marking

| Type number | Marking code |
|-------------|--------------|
| MB1F | MB1F |
| MB2F | MB2F |
| MB4F | MB4F |
| MB6F | MB6F |
| MB8F | MB8F |
| MB10F | MB10F |

